

Zhen Ding Hosts 2026 Global Partnership Conference and Groundbreaking Ceremony of the Smart Manufacturing Base at Avary's Shenzhen Campus III, Joining Forces with Global Supply Chain Partners to Build a Next-Generation High-End PCB Ecosystem for the AI Era

Zhen Ding Technology Holding Limited (Ticker: 4958), a global leading PCB manufacturer, today (July 24) held its “2026 Global Partnership Conference and Groundbreaking Ceremony of the Smart Manufacturing Base at Avary's Shenzhen Campus III.” The event brought together global business partners, government representatives and industry experts. Beyond marking the official start of construction at the new campus, the gathering represented a shared commitment by Zhen Ding and its global partners to advancing the next phase of AI-driven growth. It also underscored the Group's long-term commitment to accelerating its expansion in high-end AI applications, advancing smart manufacturing and strengthening collaboration across the global supply chain.

Speaking at the groundbreaking ceremony, Chairman Charles Shen said that AI is reshaping industries worldwide at an unprecedented pace. From AI servers and high-speed optical modules to AI devices and intelligent vehicles, high-end PCBs have become a critical part of the “infrastructure” powering modern AI systems. As AI adoption accelerates, demand for PCBs is moving rapidly toward higher density, higher layer counts and enhanced reliability, creating a new wave of growth opportunities for the global PCB industry.

Chairman Shen emphasized that the Shenzhen Campus III represents a major strategic investment supporting Zhen Ding's development in the AI era. It also marks an important step in expanding beyond the Group's established consumer electronics business and building AI-related applications into its second major growth engine. The new campus will have a planned gross floor area of approximately 500,000 square meters, with total investment expected to exceed RMB10 billion. Its production capabilities will focus on high-end substrate-like PCBs for AI servers and optical modules, as well as advanced flexible PCBs for AI devices. The campus will also incorporate smart manufacturing technologies, automated production systems and digital management platforms. The Group currently operates 28 production buildings, with another 13 under construction and 16 in the planning stage. By 2030, a total of 57 production buildings are expected to be operational, further strengthening Zhen Ding's global capacity to supply advanced PCB products.

Held later in the day, the Global Partner Conference featured presentations on the Group's future development strategy and a forum themed “Opportunities and Challenges for Heterogeneous Integration in the AI Computing Revolution.” Participants explored how the rapid expansion of AI computing is driving comprehensive upgrades across semiconductors, IC substrates, PCBs, smart manufacturing and end applications. Zhen Ding also recognized partners that have demonstrated outstanding performance in ESG, product quality, technological innovation and service.

Addressing the Global Partner Conference, Chairman Shen noted that PCBs are the foundation of electronics. Every major technology transition has expanded the PCB market while raising the technological and manufacturing requirements placed on the industry. Driven by the rapid development of AI, global PCB production value is expected to surpass US\$100 billion for the first time this year. This milestone is expected to usher in a new long-term growth cycle and mark the beginning of a “golden decade” for the PCB industry.

Chairman Shen further referenced NVIDIA CEO Jensen Huang’s “five-layer AI cake” framework, which extends from energy at the foundation to chips, AI infrastructure, models and applications. PCBs are indispensable across every layer of this technology stack. AI is driving sustained growth in PCB demand while also accelerating a broad-based upgrade in product specifications. As a result, PCBs have evolved beyond their traditional role as carriers of electrical signals and are increasingly becoming a critical determinant of AI system performance and reliability.

As technological requirements, manufacturing complexity and supply chain coordination continue to increase, competition will increasingly extend beyond individual companies to encompass entire industrial value chains and ecosystems. Chairman Shen said Zhen Ding will continue to deepen its partnerships with materials suppliers, equipment manufacturers and global supply chain participants. Through joint research and development, process innovation and resource integration, the Group aims to accelerate the commercialization of advanced PCB technologies while improving supply chain efficiency, quality and resilience. Together with its partners, Zhen Ding intends to capture the long-term growth opportunities created by the AI era.

Looking ahead, Chairman Shen said Zhen Ding will remain committed to identifying major market trends, developing advanced products and growing alongside world-class customers. The Group will continue to strengthen its One ZDT platform by integrating its comprehensive portfolio of flexible PCBs, high-layer-count PCBs, HDI products and IC substrates. Through these capabilities, Zhen Ding is actively positioning itself across the entire AI value chain, spanning “cloud, channel, and edge devices.” From AI servers and high-speed optical modules to emerging Edge AI applications such as AI glasses, humanoid robots, the low-altitude economy and brain-computer interfaces, Zhen Ding will continue to expand its global presence and work closely with partners around the world to embrace the next golden decade of the AI era.



(Above) Chairman Shen delivers a speech at the groundbreaking ceremony for the Shenzhen Third Campus.

About Zhen Ding Technology Holding Limited

Zhen Ding Technology Holding Limited (Taiwan Stock Exchange: 4958) specializes in the research, development, production, and sales of a diversified range of products, including flexible printed circuit board (FPC) and surface mount assembly (SMA), substrate-like PCBs (SLP), high-density interconnect (HDI) PCBs, high-layer-count and high-density (HLC-HDI) boards, multilayer rigid printed circuit boards (RPCB) and IC substrates (ICS). These products are widely used in end products such as computer information, consumer electronics, communications networks, automotive electronics, AI server high-speed computing, optical module and medical applications. The company offers professional one-stop shopping, full-solution services to customer worldwide. According to Prismark's global PCB industry rankings by revenue, Zhen Ding has been ranked the world's largest PCB manufacturer for nine consecutive years, from 2017 to 2025. For more detailed information, please visit the company website: www.zdtco.com.

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